

Amendments to the Claims

This listing of the Claims will replace all prior versions and listings of the claims in this patent application.

Listing of the Claims

Claims 1-25 (canceled)

26. (currently amended) A chip package method for checking an electronic package, comprising:

\_\_\_\_\_a semiconductor chip having a bottom surface with a mark used to be read by a code reader; and

\_\_\_\_\_a first bump on said bottom surface.

\_\_\_\_\_providing said electronic package with a mark; and

\_\_\_\_\_reading said mark using a laser code reader.

27. (currently amended) The chip package method of claim 26, wherein said mark comprises a bar code.

28. (currently amended) The chip package method of claim 26, wherein said mark comprises an identity for a product.

29. (currently amended) The chip package method of claim 26 further comprising a protecting structure on said mark and on said bottom surface not covered by said mark.,  
wherein said mark comprises an identity for a manufacturer.

30. (currently amended) The chip package method of claim 26 further comprising a second bump on said bottom surface, wherein said mark is between said first and second bumps.,  
wherein said electronic package comprises a semiconductor chip and a protecting structure, said semiconductor chip having a surface with said mark, said protecting structure being over said mark, wherein said mark is visible through said protecting structure.

31. (currently amended) The chip package method of claim 26-30 further comprising a protecting structure on said mark, wherein said protecting structure is non-black.,  
wherein said surface further comprises multiple pads.

32. (currently amended) The chip package method of claim 26-30 further comprising a protecting structure on said mark.,  
wherein said semiconductor chip has another surface with multiple pads.

33. (currently amended) A semiconductor chip having a top surface with a mark used to be read by a code reader and a bottom surface with multiple pads.  
An electronic package comprising a mark read by a laser code reader.

34. (currently amended) The semiconductor chip electronic package of claim 33, wherein said mark comprises a bar code.

35. (currently amended) The semiconductor chip electronic package of claim 33, wherein said mark comprises an identity for a product.

36. (currently amended) The semiconductor chip electronic package of claim 33, wherein said mark comprises an identity for a manufacturer.

37. (currently amended) The semiconductor chip electronic package of claim 33 further comprising multiple bumps on said multiple pads, a semiconductor chip and a protecting structure, said semiconductor chip having a surface with said mark, said protecting structure being over said mark, wherein said mark is visible through said protecting structure.

38. (currently amended) A chip package comprising:

a substrate;

a semiconductor chip over said substrate;

a wirebonded wire connecting said semiconductor chip and said substrate; and

a protecting structure over said semiconductor chip and said substrate, and enclosing said wirebonded wire, wherein said semiconductor chip is visible through said protecting structure.

A semiconductor chip having a surface with a mark read by a laser code reader.

39. (currently amended) The chip package semiconductor chip of claim 38, wherein said semiconductor chip has a mark used to be read by a code reader, wherein said mark is visible through said protecting structure. mark comprises a bar code.

40. (currently amended) The chip package semiconductor chip of claim 39, 38, wherein said mark comprises an identity for a product.

41. (currently amended) The chip package semiconductor chip of claim 39, 38, wherein said mark comprises a bar code. an identity for a manufacturer.

42. (currently amended) The chip package semiconductor chip of claim 38 comprising multiple balls under said substrate. , wherein said surface further comprises multiple pads.

43. (currently amended) The chip package semiconductor chip of claim 38, wherein said substrate is flexible. semiconductor chip has another surface with multiple pads.

44. (currently amended) An electronic-A chip package comprising:  
    a substrate;  
    a semiconductor chip over said substrate;  
    multiple bumps between said semiconductor chip and said substrate; and  
    a protecting structure over said semiconductor chip and said substrate, wherein said  
    semiconductor chip is visible through said protecting structure.

— a semiconductor chip having a first surface with multiple pads and a second surface with a mark; and

— a protecting structure over said mark, wherein said mark is visible through said protecting structure.

45. (currently amended) The chip electronic package of claim 44, wherein said semiconductor chip has a top surface with a mark used to be read by a code reader and covered by said protecting structure, and a bottom surface having said multiple bumps formed thereon, wherein said mark is visible through said protecting structure, wherein said mark comprises a bar code.

46. (currently amended) The chip electronic package of claim 45, 44, wherein said mark comprises a bar code number.

47. (currently amended) The chip electronic package of claim 45, 44, wherein said mark comprises an identity for a product.

48. (currently amended) The chip electronic package of claim 44 further comprising an underfill material between said semiconductor chip and said substrate, and enclosing said multiple bumps, wherein said mark comprises an identity for a manufacturer.

49. (currently amended) The chip electronic package of claim 47-44 further comprising multiple balls under said substrate, wherein said mark is colored.

50. (currently amended) A device ~~An electronic package~~ comprising:

a semiconductor chip having a top surface having a first region with a mark and a second region without said mark; and

a protecting structure over said mark and said second region, wherein said mark is visible through said protecting structure.

~~— a semiconductor chip having a surface with a mark comprising a number, a bar code, or an identity for a product or a manufacturer; and~~

~~— a protecting structure over said mark, wherein said mark is visible through said protecting structure.~~

51. (currently amended) The device ~~semiconductor chip~~ of claim 50, wherein said mark comprises a bar code. ~~, wherein said surface further comprises multiple pads.~~

52. (currently amended) The device ~~semiconductor chip~~ of claim 50, wherein said semiconductor chip has a bottom another surface with multiple pads.